

SOMATECT KZ

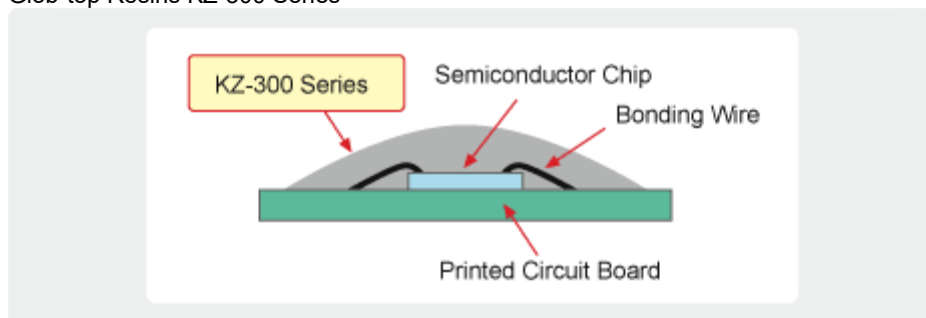
SOMATECT KZ Series are heat curable resins for semiconductor sealing. Resins for various applications such as glob-top resins, underfill resins and CSP reinforcing resins, etc. are available.

Features

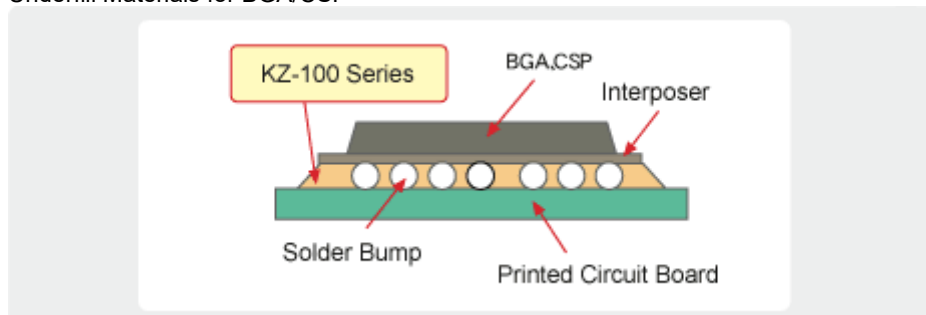
1. Easy-to-use one-part resins, and excellent in storage stability.
2. Glob-top Resins
Grades available suited for each application adjusting to flow property and substrates, etc.
3. CSP Reinforcing Resins
High reliability types used for automobile PCBs are also available.

Product Line-Up and Properties

1. Glob-top Resins KZ-300 Series



2. Underfill Materials for BGA/CSP



Application	Properties	Product Name	Curing Conditions	Viscosity	Tg Temp.	Linear Expansion Coefficient	Shelf Life (Month/°C)
Glob-top	Medium Flow/ Storage Stability	KZ-310	100°C /60min + 150°C /150min	77Pa·s	150°C	$2.3 \times 10^{-5} \text{°C}^{-1}$	6/0
BGA Reinforcing	Low Temp. Cure / Moisture Resistance	KZ-106	85°C /60min or 100°C /30min	9Pa·s	90°C	$4.5 \times 10^{-5} \text{°C}^{-1}$	6/5-10
	Low Temp. Cure / Repairability	KZ-107	80°C /45min or 120°C /5min	3Pa·s	55°C	$6.0 \times 10^{-5} \text{°C}^{-1}$	

(All numbers are representative values.)

For more information regarding this and other products, please contact us directly.



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